

Amendments to the Claims:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strike through~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously present), or (not entered).

Applicant reserves the right to pursue any cancelled claims at a later date.

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1.-10. (canceled)

11. (currently amended) A repair method for repairing a component having a base material with an oriented microstructure, comprising:

applying a solder in a region of the component to be repaired wherein the solder comprises a constituent whose melting temperature is lower than the melting temperature of the component base material; and

heating the solder by directly irradiating the solder with a laser beam;

melting the solder material by the laser beam wherein the component base material is not melted;

choosing a speed of the laser beam relative to the component or a power of the laser beam for generating a temperature gradient in the region of the component to be repaired during the heating step to produce an oriented microstructure in the repaired site which comprises the same oriented microstructure as the surrounding base material,

wherein the solder comprises a first constituent with a melting temperature lower than a melting temperature of the component base material and a second constituent having a high durability and a melting temperature greater than the first constituent melting temperature but below the base material melting temperature so that both the first constituent and the second constituent in the solder are melted by the laser beam but the component base material is not melted, wherein a first solder composition in which the first ~~constitute~~ constituent makes up a high proportion is applied first to establish a good bonding with the component base material,

and a second solder composition in which the first ~~constitute~~ constituent is reduced relative to the second ~~constitute~~ constituent is subsequently applied to ensure a high durability during subsequent operation of the component and is not removed.

12. (previously presented) The repair method as claimed in claim 11, wherein the temperature gradient is aligned so that it extends in the direction of the orientation of the oriented microstructure of the component base material.

13. (canceled).

14. (canceled).

15. (canceled).

16. (canceled).

17. (previously presented) The repair method as claimed in claim 11, wherein the base material is heat treated during the soldering step.

18. (previously presented) The repair method as claimed in claim 17, wherein the solder is in the form of a powder, paste or film.

19. (previously presented) The repair method as claimed in claim 18, wherein the solder powder is a nanopowder.

20.-25. (canceled)